

NR1689-527
App. No. 10716,553
Response to Office Action dated 4 April 2004

ABSTRACT OF THE DISCLOSURE

A solvent, such as deionized water, is heated up to boil to remove the oxygen dissolved in the water before preparing the plating solutions for the growth of copper interconnects. The resistance of the copper grown from the EDD solutions having undergone the oxygen-removing process is greatly improved, down to a value very close to copper's ideal value.

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